Tool ID: 408
Tool Location: 117

Equipment Information Sheet

Heidelberg Mask Writer - DWL2000

Manager: Garry Bordonaro 607-254-4936
Backup: Giovanni Sartorello 607-254-4853
Backup: John Treichler 607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- System uses a class IIIb laser that is interlocked with chamber door to reduce the laser class to class I

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Reservations are forfeited if the tool is not enabled within 15 minutes of the reservation start time
- No consecutive reservations by members of the same group
- Maximum 4 hour block reservations 8AM-6PM
- Maximum 2 reservations per day (for all members of the same group)
- Maximum 12 hours reserved in advance (for all members of the same group)
- 2 hours required between reservations

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Masks Only - either 0.090" or 0.250" thick
- NO wafers, pieces or other substrates

Last Updated: 02/18/2025